Supplier Name:	CARSEM (M) SDN BHD
Company Address:	Jalan Lapangan Terbang, PO Box 204, 30720 Ipoh, Perak, Malaysia
Responder Contact Name:	WAN FARIDAH
Responder Contact Phone:	605-3123333
Responder Contact email:	wanfaridah@m.carsems.com.my
Responder Title:	ESH Section Manager
Date of Response:	17th October 2008

Responder Signature:

Instructions

Suppliers must provide the identity and % weight of ALL substances of very high concern (SVHC) present in products supplied to Maxim. SVHCs are defined by REACH Article 57 and in accordance with Directive 67/548/EEC. The criteria is set out in REACH Annex XIII. For more information see http://ec.europa.eu/environment/chemicals/reach/reach_intro.htm .

The list of SVHC substances is only for the currently known candidate listing as of Oct 1 2008. Additional updates to this listing are expected and additional requests for data on those new substances as added will be sent.

Data is to supplied for each material type/formulation used in our products. Where multiple suppliers are used, worse case data (highest value) should be shown. Examples: Material Type = Mold Compound, Name/Formula = Sumitomo EME-G600. Material Type = Leadframe, Name/Formula = Cu alloy C194.

Where there is no content of the substance, enter 0%.
Insert additional rows as needed to reflect content of substances per material used.

		% Weight of Substance/CAS number																
		Anthracene (CAS No. 120-12-7)	4,4'-diaminodiphenylmethane (CAS No. 101-77-9)	Dibutyl phthalate (DBP) (CAS No. 84-74-2)	Cyclododecane (CAS No. 294-62-2)	Cobalt dichloride (CAS No. 7546-79-9)	Diarsenic pentaoxide (CAS No. 1303-28-2)	Diarsenic trioxide (CAS No. 1327-53-3)	Sodium dichromate, dihydrate (CAS No. 7789-12-0)	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) (CAS No. 81-15-2)	Bis (2-ethyl(hexyl)phthalate) (DEHP) (CAS No. 117-81-7)	Hexabromocyclododecane (HBCDD) (CAS No. 25637-99-4)	Short chain chlorinated paraffins (SCCPs) (CAS No. 85535-84-8)	Bis(tributyltin)oxide (CAS No. 56-35-9)	Lead hydrogen arsenate (CAS No. 7784-40-9)	Triethyl arsenate (CAS No. 15606-95-8)	Benzyl butyl phthalate (BBP) (CAS No. 85-68-7)
Material Type	Die Attach Epoxy																	
Material Name/Formula	Ablestik 2600BT	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Ablestik 8006NS	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Ablestik 8200C	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Ablestik 84-1LMISR4	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Ablestik 84-3J	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Henkel QMI-526	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Henkel QMI-529LB	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach Epoxy																	
Material Name/Formula	Henkel QMI-536	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	DCI Alloy 42	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	DCI C7025	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	DCI Cu194	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Hitachi CEL9220HF13	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Nitto GE-100-LFC	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Nitto HC100XG-BF1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Nitto MP8000CSM	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-6650RL-1L	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-7320AR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-7730LF	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G600	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G600C	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G700J	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G700JA	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G700L	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G770HC	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Solder Ball																	
Material Name/Formula	Profound 63SN/37PB	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Solder Paste																	
Material Name/Formula	Henkel 95Sn5Sb CR32 AGS88	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Solder Paste																	
Material Name/Formula	Indium INDALLOY 133	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrate																	
Material Name/Formula	Daisho Denshi 832EX	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrate																	
Material Name/Formula	Daisho Denshi 832HS	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrate																	
Material Name/Formula	JCI 2LBT-EL	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrate																	
Material Name/Formula	Kinsus 2LBT-ELY-0.56-C0223A	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Underfill																	
Material Name/Formula	Chipcoat U8439-1-MAX	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Underfill																	
Material Name/Formula	Hysol FP4549	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Wire																	
Material Name/Formula	Tanaka 1.0 Au	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Wire																	
Material Name/Formula	Tanaka 1.3 Au	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Wire																	
Material Name/Formula	Tanaka 2.0 Au	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0